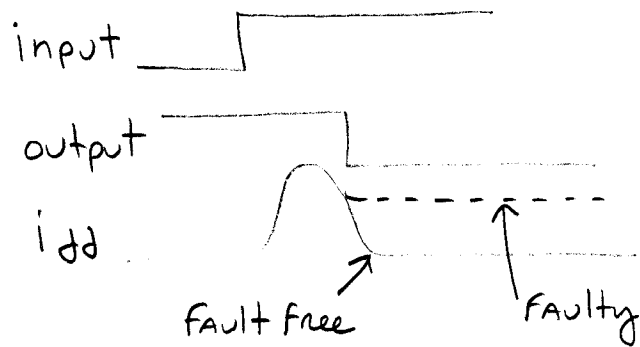
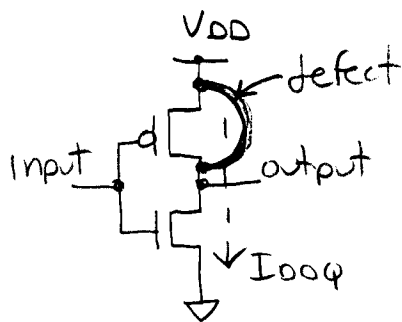


I_{DDQ} TESTING of CMOS chips

Under steady state conditions, CMOS gates do not consume power (ideally).

Some current does flow in steady state conditions that is called leakage current, denoted as I_{DDQ} .

By measuring elevated leakage current, A defective chip may be detected.



A defect that causes a high I_{DDQ} when excited is called a PATTERN dependent defect. A defect that causes a high I_{DDQ} independent of input pattern is called a PASSIVE defect.

Advantages of Iddq Testing

Since Iddq test uses power lines for fault propagation, 100% observability is possible.

Only a relatively few vectors are required to excite all possible defect sites.

Defects detected by Iddq testing also tend to reduce reliability.

- metal slivers, electromigration damage
- hot carrier injection damage

Iddq tests are very useful to screen devices used in high reliability applications.

I_{DDQ} testing of DSM CMOS

Current Signature

Run many vector sets into chip and note any large jumps in I_{DDQ} over background current.

Delta I_{DDQ}

Measure difference between minimum I_{DDQ} vector and maximum I_{DDQ} vector; reject if difference is large.

Wafer-level Spatial Correlation

Neighboring chips on wafer have fault-free I_{DDQ} characteristics. Reject those neighbors outside the norm.

Challenges to I_{DDQ} Testing

Static threshold method traditionally used

- If I_{DDQ} exceeds A threshold, the chip is rejected.

As feature sizes decrease, static threshold methods no longer work.

$$I_{DDQ} \approx \left(\frac{W \cdot X_c}{L_{eff}} \right) e^{-\frac{K V_T}{T}}$$

- K = Boltzman const.
- W · X_c = channel cross sectional current flow area
- W = channel width
- L_{eff} = effective channel length
- V_T = device threshold voltage
- T = device temperature

To operate with much thinner gate oxides, V_T must be reduced. This causes an exponential increase in leakage current.

For current high performance DSM technology, leakage currents are on the order of a few hundred mA.

Future technologies will produce leakage currents in the 10's of Amperes. (8 to 20 A by 2014)

I_{DDQ} testing is slow. 10 - 100 m\$ per measurement